15	214488	slurry or slurries	USPAT;	2002/04/01
13	214466	Stuffy of Stuffles	US-PGPUB;	14:47
ł			EPO; JPO;	13.37
		,	DERWENT;	
			IBM TDB	
16	48	(planariz\$4 and (solder\$3 near3 (bump or	USPAT;	2002/04/01
		ball))) and (slurry or slurries)	US-PGPUB;	14:47
		-	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
17	183941	dissolve or disolve	USPAT;	2002/04/01
			US-PGPUB;	14:47
		·	EPO; JPO;	
			DERWENT;	
1.0	677501	14 1 - 42	IBM_TDB	2002/04/01
18	677591	dissolv\$3	USPAT;	2002/04/01 14:48
			US-PGPUB; EPO; JPO;	14:40
			DERWENT;	
			IBM TDB	
19	1714	disolv\$3	USPAT;	2002/04/01
	1		US-PGPUB;	14:48
			EPO; JPO;	
	İ	*	DERWENT;	
			IBM_TDB	
20	87	(planariz\$4 and (solder\$3 near3 (bump or	USPĀT;	2002/04/01
		ball))) and (dissolv\$3 or disolv\$3)	US-PGPUB;	14:48
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
21	23	((planariz\$4 and (solder\$3 near3 (bump or	USPAT;	2002/04/01
		ball))) and (dissolv\$3 or disolv\$3)) and	US-PGPUB;	14:48
		(slurry or slurries)	EPO; JPO;	·* .
	Ì		DERWENT;	
22	321	(solder\$3 near3 (bump or ball)) same	<pre>IBM_TDB USPAT;</pre>	2002/04/01
22	321	(dissolv\$3 or disolv\$3)	US-PGPUB;	14:51
	1	(dissolves of disolves)	EPO; JPO;	14.51
			DERWENT;	
		•	IBM TDB	
23	13	((solder\$3 near3 (bump or ball)) same	USPAT;	2002/04/01
		(dissolv\$3 or disolv\$3)) same planariz\$4	US-PGPUB;	14:49
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
24	19	((solder\$3 near3 (bump or ball)) same	USPAT;	2002/04/01
		(dissolv\$3 or disolv\$3)) and planariz\$4	US-PGPUB;	14:51
			EPO; JPO;	
1			DERWENT;	•
25	6	///goldones name /humm on halling game	IBM_TDB USPAT;	2002/04/01
23	9	(((solder\$3 near3 (bump or ball)) same (dissolv\$3 or disolv\$3)) and planariz\$4)	USPAT; US-PGPUB;	14:54
		not (((solder\$3 near3 (bump or ball))	EPO; JPO;	11.51
		same (dissolv\$3 or disolv\$3)) same	DERWENT;	
		planariz\$4)	IBM TDB	
26	3956	abrasive near2 (slurry or slurries)	USPAT;	2002/04/01
		,,	US-PGPUB;	14:55
			EPO; JPO;	
			DERWENT;	1
			IBM_TDB	
27	15	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2002/04/01
		same (solder\$3 near3 (bump or ball))	US-PGPUB;	14:55
			EPO; JPO;	
			DERWENT;	
120		///	IBM_TDB	2002/04/01
29	0	[(((, , , , , , , , , , , , , , ,	USPAT;	2002/04/01
		same (solder\$3 near3 (bump or ball))) and planariz\$4) not (((solder\$3 near3 (bump	US-PGPUB; EPO; JPO;	14.33
		or ball)) same (dissolv\$3 or disolv\$3))	DERWENT;	
		same planariz\$4)	IBM TDB	
	1	Louis Standtrada)	1	1

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((polyammonium\$1acrylate) or (polyammonium adj acrylate) or (polyamine\$1acrylate) or (polyamine adj acrylate)) with mixed with water

((polyammonium\$1acrylate) or (polyammonium adj acrylate) or (polyamine\$1acrylate) or (polyamine adj acrylate)) same water

((polyammonium\$1acrylate) or (polyammonium adj acrylate) or (polyamine\$1acrylate) or (polyamine adj acrylate)) same dispersant same water

abrasive and ((polyammonium\$1acrylate) or (polyammonium adj acrylate) or (polyamine\$1acrylate) or (polyamine adj acrylate))

cmp and ((polyammonium\$1acrylate) or (polyammonium adj acrylate) or (polyamine\$1acrylate) or (polyamine adj acrylate))